

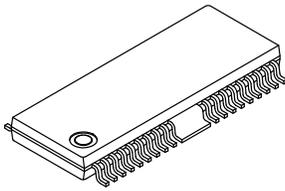
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



HSSOP36 (275 mil)
CASE 943AH
ISSUE A

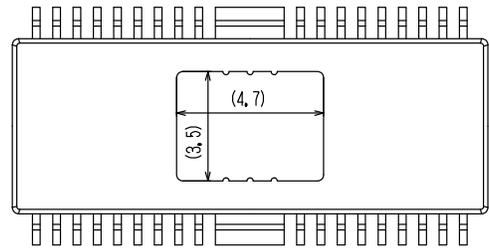
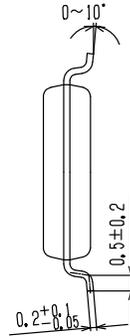
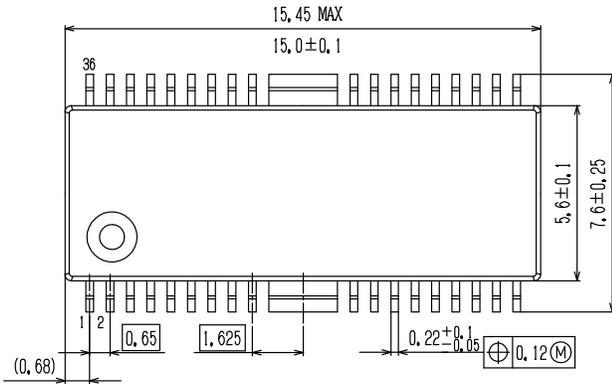
DATE 25 NOV 2013



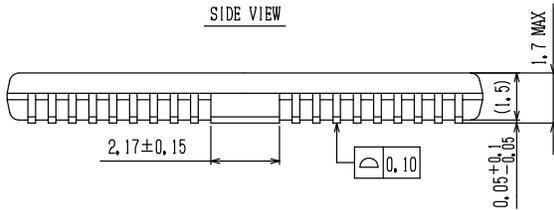
TOP VIEW

SIDE VIEW

BOTTOM VIEW



SIDE VIEW



GENERIC MARKING DIAGRAM*

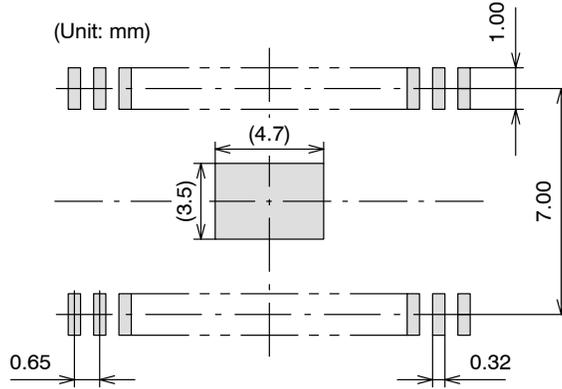


XXXXX = Specific Device Code
Y = Year
M = Month
DDD = Additional Traceability Data

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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DESCRIPTION:	HSSOP36 (275 MIL)	PAGE 1 OF 3

SOLDERING FOOTPRINT*



NOTES:

1. The measurements are for reference only, and unable to guarantee.
2. Please take appropriate action to design the actual Exposed Die Pad and Fin portion.
3. After setting, verification on the product must be done.
 (Although there are no recommended design for Exposed Die Pad and Fin portion Metal mask and shape for Through-Hole pitch (Pitch & Via etc), checking the soldered joint condition and reliability verification of soldered joint will be needed. Void ▫ gradient ▫ insufficient thickness of soldered joint or bond degradation could lead IC destruction because thermal conduction to substrate becomes poor.)

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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